



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Takenori HIROSE, et al.

Application No.: 10/081,385

Filed: February 20, 2002

For: Film Thickness Measuring Method
and Apparatus, and Thin Film Device
Manufacturing Method and Manufacturing
Apparatus Using Same

Customer No.: 20350

Confirmation No. 9702

Examiner: Hwa S. Lee

Technology Center/Art Unit: 2877

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Office Action mailed June 15, 2004, on the above-referenced application, please enter the following amendments and remarks:

Amendments to the Claims are reflected in the Listing of Claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 7 of this paper.